

**Marked-Up Version of Amended Claims**

1. (Amended) A chip scale package comprising:

a leadframe including a die attach pad centrally located therein and a plurality of wire bonding pads peripherally located therein;

at least one aperture formed in the die attach pad;

at least one die formed on the die attach pad;

at least one bonding wire for electrically connecting the at least one die and at least of of the plurality of wire bonding pads; and

a mold compound, wherein said mold compound encapsulates [for encapsulating] the at least one die and the at least one bonding wire to form a chip scale package, and wherein the mold compound resides [is formed in] the at least one aperture.

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